

The US Particle Accelerator School Ion Pumps

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Penning Cell



Pumping mechanism



- Electrical discharge takes place in crossed electric and magnetic fields.
- The Titanium cathode is bombarded by positive ions.
- Titanium is sputtered on to to the walls of the anode.
- Gas chemisorbs to the sputtered Titanium.
- Gas is buried in the Titanium cathode.



Physisorption - atom burial deep within a lattice, atom burial under sputtered material.

Chemisorption – removal of atoms due to the formation of chemical bonds.

Diffusion - hydrogen diffuses into the bulk of the metal.



Sputter-ion pump characteristics

- Pumping speed is sensitive to gas species, inlet size, pressure, and history of pump
- Starting pressure ion pumps must be roughed to 20 milliTorr or less before starting (should be more like 10⁻⁶ Torr)
- Capacity sputter ion pumps are gas capture type pumps and do have a limited capacity
- Ultra clean
- · Quiet
- High pumping speed for water, hydrogen
- Gas species sensitive
- Limited capacity

Advantages

Disadvantages



Penning Cell Sensitivity

$$S = \frac{I^+}{P}$$

Where I⁺ = ion current (Amps) P = pressure (Torr)

Parameters that effect Penning Cell Sensitivity and typical values

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Anode Voltage	
Magnetic Field	
Cell Diameter	
Cell Length	
Anode/Cathode Gap	
Pressure (P ⁿ)	

3.0 - 7.0 kV 0.1 - 0.2 T 1.0 - 3.0 cm 1.0 - 3.2 cm 0.6 - 1.0 cm1.05 < n < 1.5 Torr

Penning cell sensitivity as a function of magnetic field and anode potential





(Ref., Welch, SLAC, 1969)

Penning cell sensitivity as a function of magnetic field and anode-to-cathode spacing

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Types of sputter-ion pumps

- Diode best for UHV systems where 98% of the gas is hydrogen. Diodes have the highest hydrogen pumping speed.
- Differential (Noble Diode) a compromise for hydrogen pumping speed with limited argon stability. This pump has reduced hydrogen pumping speed.
- Triode/Starcell good hydrogen pumping speed, also pumps argon well. Good choice for pumping down from higher pressures often.



Diode sputter-ion pump





Argon Instability

• Diode ion pumps produce large periodic pressure fluctuations while pumping air or gas mixtures containing inert gases.

- These fluctuations are called "argon instability."
- Argon instability occurs both when pumping air at HV or UHV (1% argon by volume) and pure argon or other inert gases.
- Argon instability occurs when implanted or buried gases are released by sputtering.
- An "argon-stable" pump is one that can pump against a 100% argon leak without becoming unstable.





Differential Ion (Noble Diode) Pumps

- The differential ion (D-I) pump design provides both air-stability and argonstability, in a single pump.
- Most inert gases are pumped on the anode structure and at the peripheral areas of the cathode where the sputtering rate is so low that total reemission does not occur.
- These peripheral areas and the anode surfaces are readily reached by energetic reflected neutrals because the neutrals are not affected by the magnetic field.
- With a higher rate of energetic, reflected neutral formation, inert gas pumping speed is increased.
- To achieve high inert gas pumping speeds, differential pumping elements with one cathode chosen for good energetic neutral production (tantalum) and one chosen for its chemical reactivity (titanium) are used.



Pumping speeds of ion pumps for selected gases



Gas	Noble Diode	Diode
H ₂	160%	220%
CO2	100%	100%
N ₂	85%	85%
0 ₂	70%	70%
H₂O	100%	100%
Ar	20%	5%
He	15%	2%
Light Hydrocarbons	90%	90%

Triode ion pump







• Varian Starcell pump is a variation of the triode design.







Speed curve for an ion pump









Speed comparison of different styles of ion pumps







Commercial sputter-ion pumps





Sputter-ion pump controller



(Ref: Varian Vacuum)

Sputter ion pump current may be used to measure pressure in the pump body



- Pressure is linearly proportional to current.
- At low pressures (<10⁻⁹ Torr), the leakage current effects the pressure reading.
 - The displayed current is the total of the leakage in the power supply, cable connectors, feedthroughs, insulators, internal discharge, and working current.
 - The new controllers with variable voltage capability improve this feature.



(Ref: Varian Vacuum)

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"Variable Voltage Control" also improves pump performance









- It is important to match the power supply to the ion pump.
 - Too large a power supply can create overheating in the electrodes.
 - Too small a power supply will not be able to drive the pump at higher pressures.
 - The power supply must provide voltage and current to the ion pump under a variety of conditions.



(Ref: Varian Vacuum)

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Example – Ion Pumped Vacuum System SNS Linac



Current Design Features:

Accelerator Length

DTL: 36.5 m CCL: 56.5 m

Design Vacuum Level: 10 -7 Torr (with redundancy)

Total Ion Pump Speed: 20,000 L/s

Number of Roughing/Turbo Carts: 15



Distributed Ion Pumps (DIPs)



- Distributed ion pumps are often incorporated into storage rings.
- · Distributed ion pumps utilize the stray magnetic field of the arc bend magnets.



· They provide effective distributed pumping close to synchrotron radiation gas desorption.





Pump Sensitivity (Discharge Intensity) vs. Magnetic Field





Formalism of Ion Pump Design



In cases where the magnetic field lines are misaligned with the cell axis, the electron cloud will be smaller than the anode radius.



Magnetic Field at the Ignition Point

$$B_i = \frac{300}{r_a}$$

where a = gap (cm) r_a = cell radius (cm) mode I_a = anode length (cm) P = pressure (Torr) U_a = anode voltage (V) B = magnetic field (Gauss)

Magnetic Field at the Transition to HMF-mode

$$\boldsymbol{B}_{tr} = \frac{7.63\sqrt{U_a}}{r_a P^{0.05}}$$

Effective Cell Length

$$I_{eff} = I_{a} + 0.5\alpha$$

Formalism of Ion Pump Design (continued)

Unsaturated Nitrogen Pumping Speed of one cell

$$LMF - \text{mod } e, B_i \le B \le 2B_i$$

$$S_1 = 6.27 \times 10^{-5} \left(1 - \frac{1.5 \times 10^6 P}{1 + 4 \times 10^6 P} \right) P^{0.2} I_{eff} r_a^2 B_i (B - B_i)$$

$$LMF - \mod e, \ 2B_{i} \le B \le B_{rr}$$
$$S_{1} = 1.56 \times 10^{-5} \left(1 - \frac{1.5 \times 10^{6} P}{1 + 4 \times 10^{6} P}\right) P^{0.2} I_{eff} r_{a}^{2} B^{2}$$

$$HMF - \mod e, B \ge B_{tr}$$

$$S_{1} = 9.1 \times 10^{-4} \left(1 - \frac{1.5 \times 10^{6} P}{1 + 4 \times 10^{6} P} \right) P^{0.1} I_{eff} U_{a} \left(1 - 1.5 \times 10^{4} \frac{\sqrt{(B - B_{tr}) r_{a} P}}{U_{a}} \right)$$

Saturated Nitrogen Pumping Speed (after Q = 2 x 10⁻⁶S Torr-liters/sec) multiply above equations by $\left(0.75 - \frac{2 \times 10^{-10}}{P}\right)$ valid for P > 3 x 10⁻¹⁰ Torr

$$S_{sat} = 0$$
 valid for P < 3 x 10⁻¹⁰ Torr



Nitrogen Pumping Speed for n cells

$$S_n = nS_1$$

Effective Nitrogen Pumping Speed due to conductances of the gaps between the anode and the two cathodes.

$$S_{eff} = S_n \left(\frac{\tanh D}{D}\right) \quad where \quad D = \frac{ka}{7.85\alpha} \sqrt{\frac{S_n}{ab}}$$

$$a = depth \text{ of pump unit (cm)}$$

$$b = length \text{ of pump unit (cm)}$$

$$a = gap (cm)$$

$$k = factor = 1 \text{ if pump is open on one side}$$

$$= 0.5 \text{ if pump is open on two sides}$$



Effective Nitrogen Pumping Speed for N units at the flange

$$\frac{1}{S_p} = \frac{1}{NS_{eff}} + \frac{1}{C}$$

where S_p = effective nitrogen pumping speed (liters/sec) N = number of pumping units C = conductance of the pump chamber (liters/sec)